



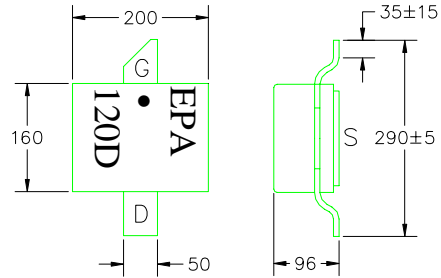
# EPA120D-CP083

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## High Efficiency Heterojunction Power FET

### FEATURES

- NON-HERMETIC SURFACE MOUNT
- 160MIL METAL CERAMIC PACKAGE
- +29 dBm OUTPUT POWER AT 1dB COMPRESSION
- 18.0 dB GAIN AT 2 GHz
- 0.5x1200 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY



All Dimensions in mil  
Tolerance: ± 3 mil



Caution! ESD sensitive device.

### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25°C)

SYMBOL	PARAMETER/TEST CONDITIONS		MIN	TYP	MAX	UNITS
P <sub>1dB</sub>	Output Power at 1dB Compression	f = 2.0 GHz V <sub>ds</sub> = 8 V, I <sub>ds</sub> =50% I <sub>dss</sub>	27.5	29.0		dBm
G <sub>1dB</sub>	Gain at 1dB Compression	f = 2.0 GHz V <sub>ds</sub> = 8 V, I <sub>ds</sub> =50% I <sub>dss</sub>	16.5	18.0		dB
PAE	Power Added Efficiency at 1dB Compression	f = 4.0 GHz V <sub>ds</sub> = 8 V, I <sub>ds</sub> =50% I <sub>dss</sub>		44		%
I <sub>DSS</sub>	Saturated Drain Current	V <sub>DS</sub> = 3 V, V <sub>GS</sub> = 0 V	210	360	510	mA
G <sub>M</sub>	Transconductance	V <sub>DS</sub> = 3 V, V <sub>GS</sub> = 0 V	240	380		mS
V <sub>P</sub>	Pinch-off Voltage	V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 3.6 mA		-1.0	-2.5	V
BV <sub>GD</sub>	Drain Breakdown Voltage	I <sub>GD</sub> = 1.2 mA	-13	-15		V
BV <sub>GS</sub>	Source Breakdown Voltage	I <sub>GS</sub> = 1.2 mA	-7	-14		V
R <sub>TH</sub> *	Thermal Resistance			45	50	°C/W

Notes: \* Overall R<sub>th</sub> depends on case mounting.

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-5V	-3V
I <sub>gsf</sub>	Forward Gate Current	5.4 mA	1.8 mA
I <sub>gsr</sub>	Reverse Gate Current	0.9 mA	0.3 mA
P <sub>in</sub>	Input Power	26 dBm	@ 3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	175°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/175°C
P <sub>t</sub>	Total Power Dissipation	3.0 W	3.0 W

Note: 1. Exceeding any of the above ratings may result in permanent damage.  
2. Exceeding any of the above ratings may reduce MTTF below design goals.

Specifications are subject to change without notice.

Excelics Semiconductor, Inc. 310 De Guigne Drive, Sunnyvale, CA 94085  
Phone: 408-737-1711 Fax: 408-737-1868 Web: [www.excelics.com](http://www.excelics.com)

page 1 of 1  
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